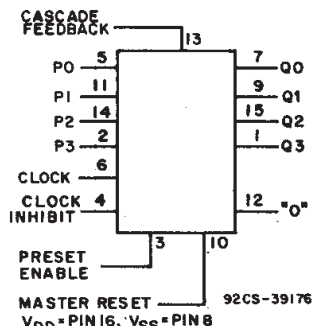


NOT RECOMMENDED FOR NEW DESIGNS

# CD4522B Types

Advance Information/  
Preliminary Data



**FUNCTIONAL DIAGRAM**

## CMOS Programmable BCD Divide-by-“N” Counter

High-Voltage Types (20-Volt Rating)

**Features:**

- Internally synchronous for high internal and external speeds.
- Logic edge-clocked design — increments on positive Clock transition or on negative Clock Inhibit transition.
- 100% tested for quiescent current at 20-V.
- 5-V, 10-V, and 15-V parametric ratings.

- Standard symmetrical output characteristics.
- Maximum input current of 1  $\mu$ A at 18 V over full package-temperature range: 100 nA at 18 V and 25° C.
- Meets all requirements of JEDEC Standard No. 13B, “Standard Specifications for Description of ‘B’ Series CMOS Devices.”

■ CD4522B programmable BCD counter has a decoded “0” state output for divide-by-N applications. In single stage operation the “0” output is tied to the Preset Enable input. The Cascade Feedback allows multiple stage divide-by-N operation without the need for external gating. A HIGH on the Clock Inhibit disables the pulse-counting function. A HIGH on the Master Reset asynchronously resets the divide-by-N operation. The output is presented in BCD format.

**Applications:**

- Frequency synthesizers
- Phase-locked loops
- Programmable down counters
- Programmable frequency dividers

The CD4522B-series types are supplied in 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (M, M96, MT, and NSR suffixes), and 16-lead thin shrink small-outline packages (PW and PWR suffixes).

**MAXIMUM RATINGS, Absolute-Maximum Values:**

<b>DC SUPPLY-VOLTAGE RANGE, (V<sub>DD</sub>)</b>	
Voltages referenced to V <sub>SS</sub> Terminal) .....	-0.5V to +20V
<b>INPUT VOLTAGE RANGE, ALL INPUTS</b> .....	
DC INPUT CURRENT, ANY ONE INPUT .....	-0.5V to V <sub>DD</sub> +0.5V
<b>POWER DISSIPATION PER PACKAGE (P<sub>D</sub>):</b>	
For T <sub>A</sub> = -55°C to +100°C .....	500mW
For T <sub>A</sub> = +100°C to +125°C .....	Derate Linearly at 12mW/°C to 200mW
<b>DEVICE DISSIPATION PER OUTPUT TRANSISTOR</b>	
FOR T <sub>A</sub> = FULL PACKAGE-TEMPERATURE RANGE (All Package Types).....	100mW
<b>OPERATING-TEMPERATURE RANGE (T<sub>A</sub>)</b> .....	
STORAGE TEMPERATURE RANGE (T <sub>stg</sub> ) .....	-55°C to +125°C
<b>LEAD TEMPERATURE (DURING SOLDERING):</b>	
At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max .....	+265°C

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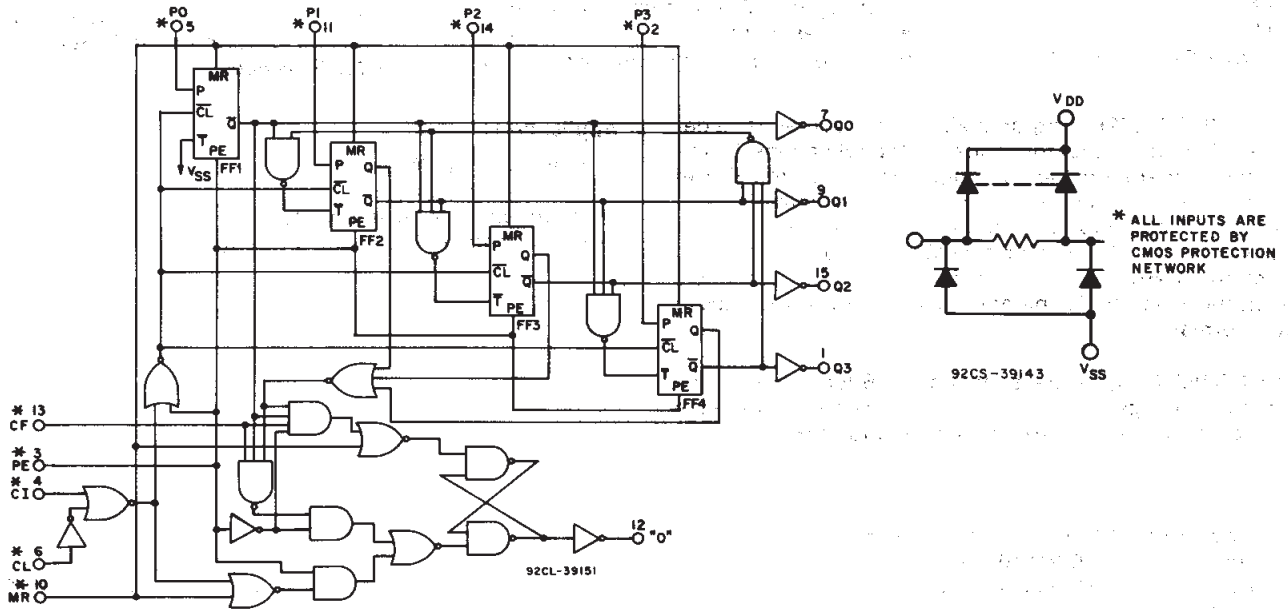
# CD4522B Types

## TRUTH TABLES

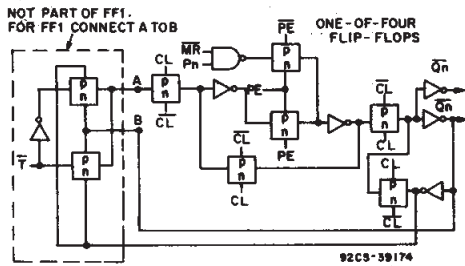
CLOCK	CLOCK INHIBIT	PRESET ENABLE	MASTER RESET	ACTION
0	0	0	0	No Count
0	0	0	0	Count Down
X	1	0	0	No Count
1	0	0	0	Count Down
X	X	1	0	Preset
X	X	X	1	Reset

X = Don't Care

Count	OUTPUTS			
	Q <sub>0</sub>	Q <sub>1</sub>	Q <sub>2</sub>	Q <sub>3</sub>
0	0	0	0	0
1	1	0	0	0
2	0	1	0	0
3	1	1	0	0
4	0	0	1	0
5	1	0	1	0
6	0	1	1	0
7	1	1	1	0
8	0	0	0	1
9	1	0	0	1



a. Basic diagram.



b. Flip-flop detail.

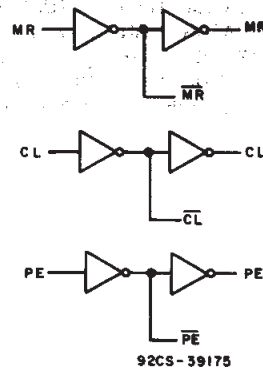


Fig. 1 - Logic diagram for the CD4522B.

## CD4522B Types

**RECOMMENDED OPERATING CONDITIONS** at  $T_A = 25^\circ\text{C}$ , except as noted.

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTICS	$V_{DD}$ (V)	LIMITS		UNITS
		Min.	Max.	
Supply-Voltage Range (For $T_A =$ Full Package-Temperature Range)		3	18	V
Pulse Width:	5	250	—	ns
Clock, $t_w(cc)$	10	100	—	
Preset Enable, $t_w(cc)$	15	80	—	
	5	250	—	ns
Preset Enable, $t_w(cc)$	10	100	—	
Master Reset, $t_w(MR)$	15	80	—	
	5	350	—	ns
Master Reset, $t_w(MR)$	10	250	—	
Master Reset, $t_w(MR)$	15	200	—	
Clock Frequency, $f_{CL}$	5	—	1.5	MHz
	10	—	3.0	
	15	—	4.0	
Clock Rise and Fall Time $t_{rCL}, t_{fCL}$	5	—	15	$\mu\text{s}$
	10	—	15	
	15	—	15	
Preset Enable Set-up Time, $t_{su}$	5	0	—	ns
	10	0	—	
	15	0	—	
Preset Enable Hold Time, $t_h$	5	75	—	ns
	10	25	—	
	15	20	—	
Master Reset Removal Time, $t_{rem}$	5	130	—	ns
	10	50	—	
	15	30	—	

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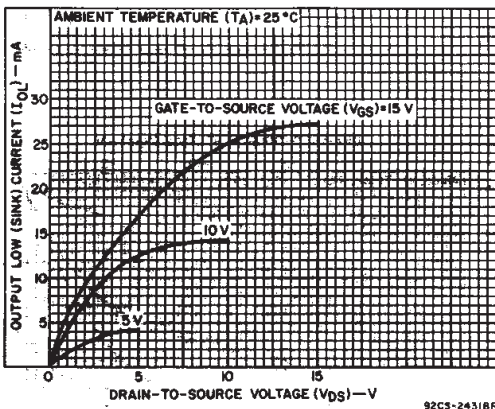


Fig. 2 — Typical output low (sink) current characteristics.

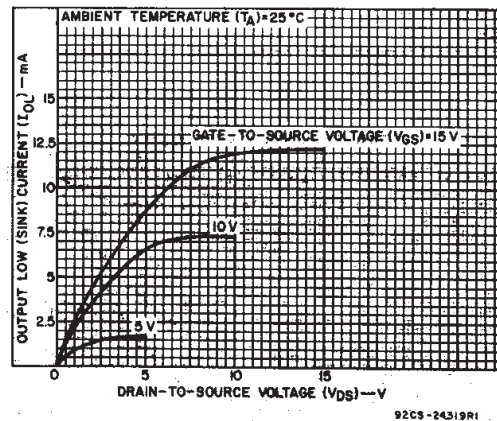
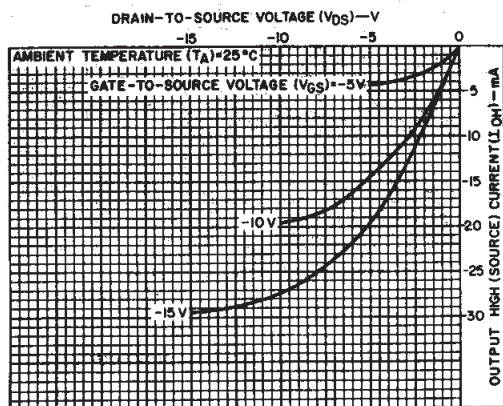


Fig. 3 — Minimum output low (sink) current characteristics.

# CD4522B Types

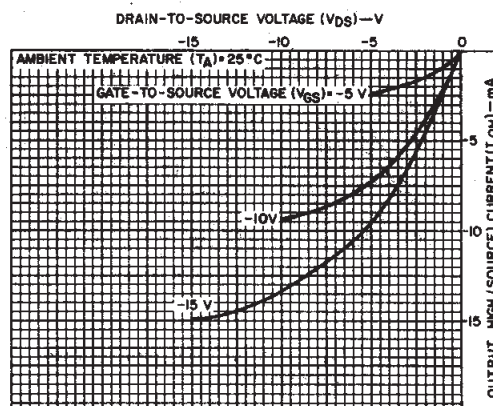
## STATIC ELECTRICAL CHARACTERISTICS

CHARACTER- ISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
	V <sub>O</sub> (V)	V <sub>IN</sub> (V)	V <sub>DD</sub> (V)					+25			
				-55	-40	+85	+125	Min.	Typ.	Max.	
Quiescent Device Current, I <sub>DD</sub> Max.	—	0, 5	5	5	5	150	150	—	0.04	5	μA
	—	0, 10	10	10	10	300	300	—	0.04	10	
	—	0, 15	15	20	20	600	600	—	0.04	20	
	—	0, 20	20	100	100	3000	3000	—	0.08	100	
Output Low (Sink) Current I <sub>OL</sub> Min.	0.4	0, 5	5	0.64	0.61	0.42	0.36	0.51	1	—	mA
	0.5	0, 10	10	1.6	1.5	1.1	0.9	1.3	2.6	—	
	1.5	0, 15	15	4.2	4	2.8	2.4	3.4	6.8	—	
	4.6	0, 5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	—	
Output High (Source) Current, I <sub>OH</sub> Min.	2.5	0, 5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	—	mA
	9.5	0, 10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	—	
	13.5	0, 15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	—	
	—	0, 5	5	0.05				—	0	0.05	
Output Voltage: Low-Level, V <sub>OL</sub> Max.	—	0, 10	10	0.05				—	0	0.05	V
	—	0, 15	15	0.05				—	0	0.05	
	—	0, 5	5	4.95				4.95	5	—	
Output Voltage: High-Level V <sub>OH</sub> Min.	—	0, 10	10	9.95				9.95	10	—	V
	—	0, 15	15	14.95				14.95	15	—	
	0.5, 4.5	—	5	1.5				—	—	1.5	
Input low Voltage, V <sub>IL</sub> Max.	1, 9	—	10	3				—	—	3	V
	1.5, 13.5	—	15	4				—	—	4	
	0.5, 4.5	—	5	3.5				3.5	—	—	
Input High Voltage, V <sub>IH</sub> Min.	1, 9	—	10	7				7	—	—	V
	1.5, 13.5	—	15	11				11	—	—	
	—	0, 18	18	±0.1	±0.1	±1	±1	—	±10 <sup>-5</sup>	±0.1	



92CS-24520R3

Fig. 4 — Typical output high (source) current characteristics.



92CS-24321R2

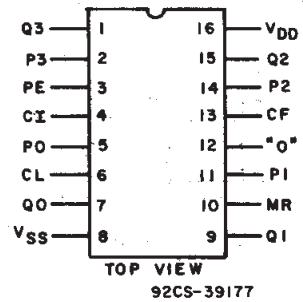
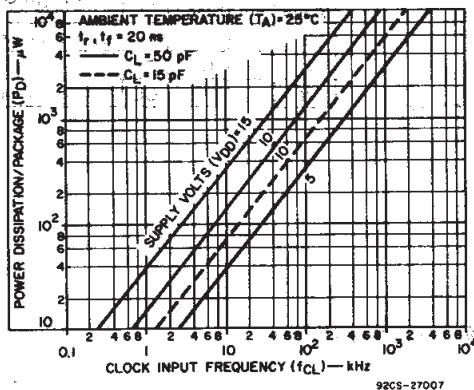
Fig. 5 — Minimum output high (source) current characteristics.

## CD4522B Types

**DYNAMIC ELECTRICAL CHARACTERISTICS at  $T_A = 25^\circ\text{C}$ , Input  $t_r, t_f = 20\text{ ns}$ ,  $C_i = 50\text{ pF}$ ,  $R_L = 200\text{ k}\Omega$**

CHARACTERISTIC	TEST CONDITIONS	LIMITS			UNITS	
		$V_{DD}$ (V)	Min.	Typ.		Max.
Propagation Delay Time; $t_{PHL}, t_{PLH}$ Clock to "Q" outputs		5	—	550	1100	ns
		10	—	225	450	
		15	—	160	320	
Clock to "0" output		5	—	420	710	ns
		10	—	160	270	
		15	—	110	190	
Clock inhibit to "Q" outputs		5	—	270	540	ns
		10	—	100	200	
		15	—	70	140	
Master reset to "Q" outputs		5	—	270	540	ns
		10	—	100	200	
		15	—	70	140	
Preset Enable Setup Time, $t_{su}$		5	—	0	0	ns
		10	—	0	0	
		15	—	0	0	
Preset Enable Hold Time, $t_h$		5	—	75	150	ns
		10	—	25	50	
		15	—	20	40	
Master Reset Removal Time, $t_{rem}$		5	—	130	260	ns
		10	—	50	100	
		15	—	30	60	
Transition Time, $t_{THL}, t_{TLH}$		5	—	100	200	ns
		10	—	50	100	
		15	—	40	80	
Minimum Pulse Width Clock, $t_{W(CL)}$		5	—	125	250	ns
		10	—	50	100	
		15	—	40	80	
Preset Enable, $t_{W(PE)}$		5	—	125	250	ns
		10	—	50	100	
		15	—	40	80	
Master Reset, $t_{W(MR)}$		5	—	175	350	ns
		10	—	125	250	
		15	—	100	200	
Max Clock Freq, $f_{CL}$		5	—	3	1.5	MHz
		10	—	6	3.0	
		15	—	8	4.0	
Max Clock or Clock Inhibit Rise & Fall Time, $t_{TLH}, t_{THL}$		5	—	—	15	us
		10	—	—	15	
		15	—	—	15	
Input Capacitance, $C_{IN}$	Any Input	—	—	5	7.5	pF

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**TERMINAL ASSIGNMENT**

**Fig. 6 — Typical dynamic power dissipation vs. frequency.**

## CD4522B Types

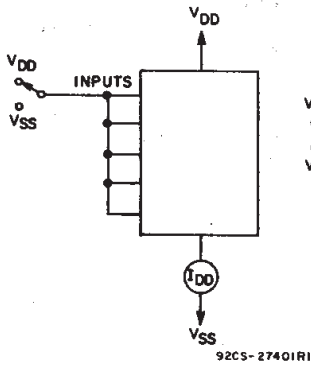


Fig. 7 — Quiescent device current test circuit.

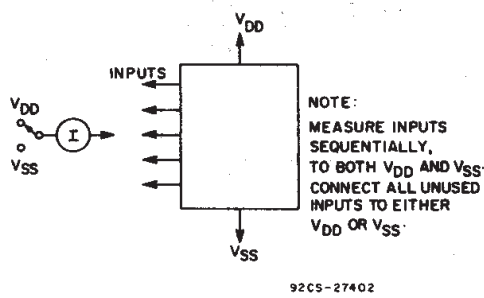


Fig. 8 — Input current test circuit.

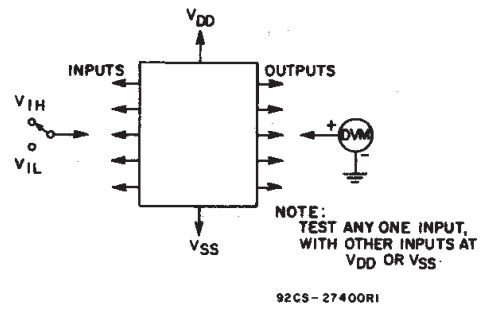


Fig. 9 — Input voltage test circuit.

## APPLICATION CIRCUITS

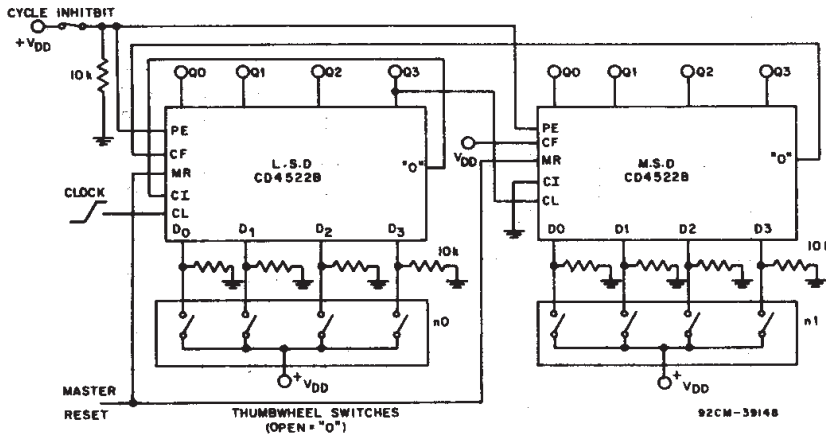


Fig. 10 — 2-Stage Programmable Down Counter (One Cycle)

From		To		Range of N
Stage	Pin	Stage	Pin	
LSD	"0"	All	PE	LSD < N < MSD
N	"0"	N-1	CF	LSD + 1 < N < MSD
N	"0 <sub>3</sub> "	N+1	CL	LSD < N < MSD-1

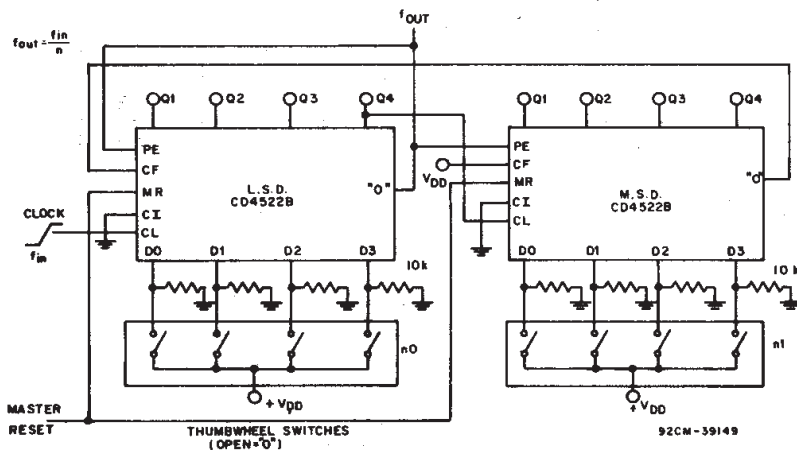
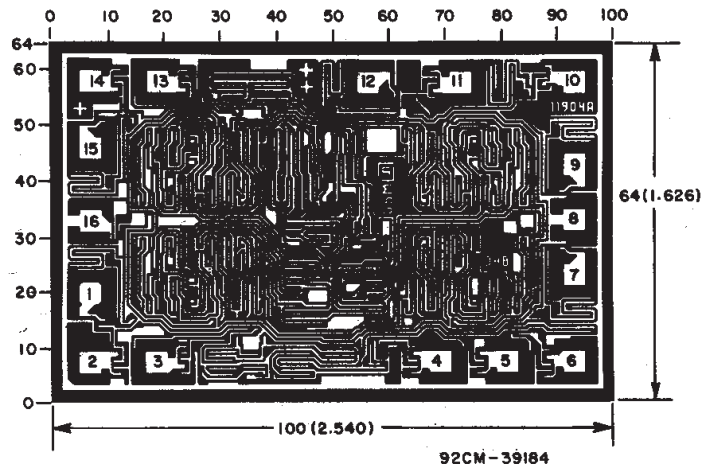


Fig. 11 — 2-Stage Programmable Frequency Divider

From		To		Range of N
Stage	Pin	Stage	Pin	
LSD	"0"	All	PE	LSD < N < MSD
N	"0"	N-1	CF	LSD + 1 < N < MSD
N	"0 <sub>3</sub> "	N+1	CL	LSD < N < MSD-1

## CD4522B Types



*Dimensions and pad layout for CD4522BH.*

*Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils ( $10^{-3}$  inch).*

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**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
CD4522BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD4522BE	<a href="#">Samples</a>
CD4522BEE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD4522BE	<a href="#">Samples</a>
CD4522BM	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4522BM	<a href="#">Samples</a>
CD4522BME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4522BM	<a href="#">Samples</a>
CD4522BMG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4522BM	<a href="#">Samples</a>
CD4522BMT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4522BM	<a href="#">Samples</a>
CD4522BMTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4522BM	<a href="#">Samples</a>
CD4522BMTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4522BM	<a href="#">Samples</a>
CD4522BPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM522B	<a href="#">Samples</a>
CD4522BPWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM522B	<a href="#">Samples</a>
CD4522BPWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM522B	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.



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**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> Only one of markings shown within the brackets will appear on the physical device.

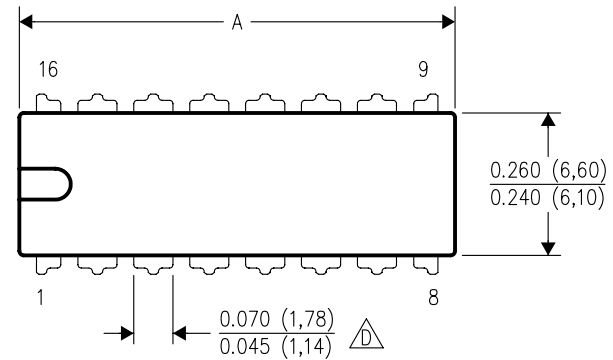
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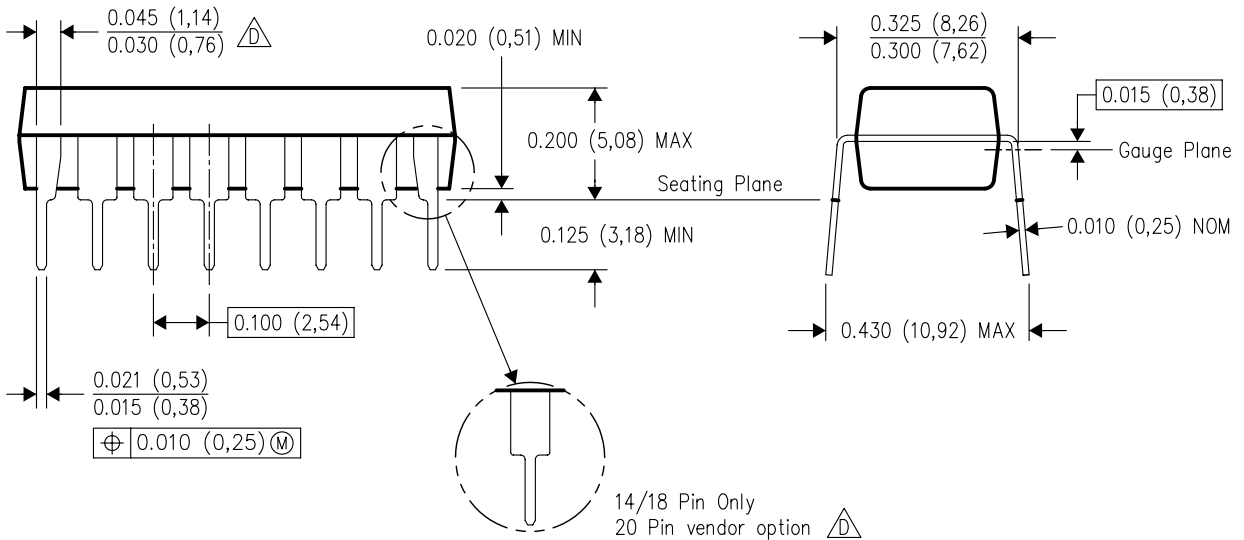
N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



DIM	PINS **			
	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4040047-6/M 06/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  -  C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  -  D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

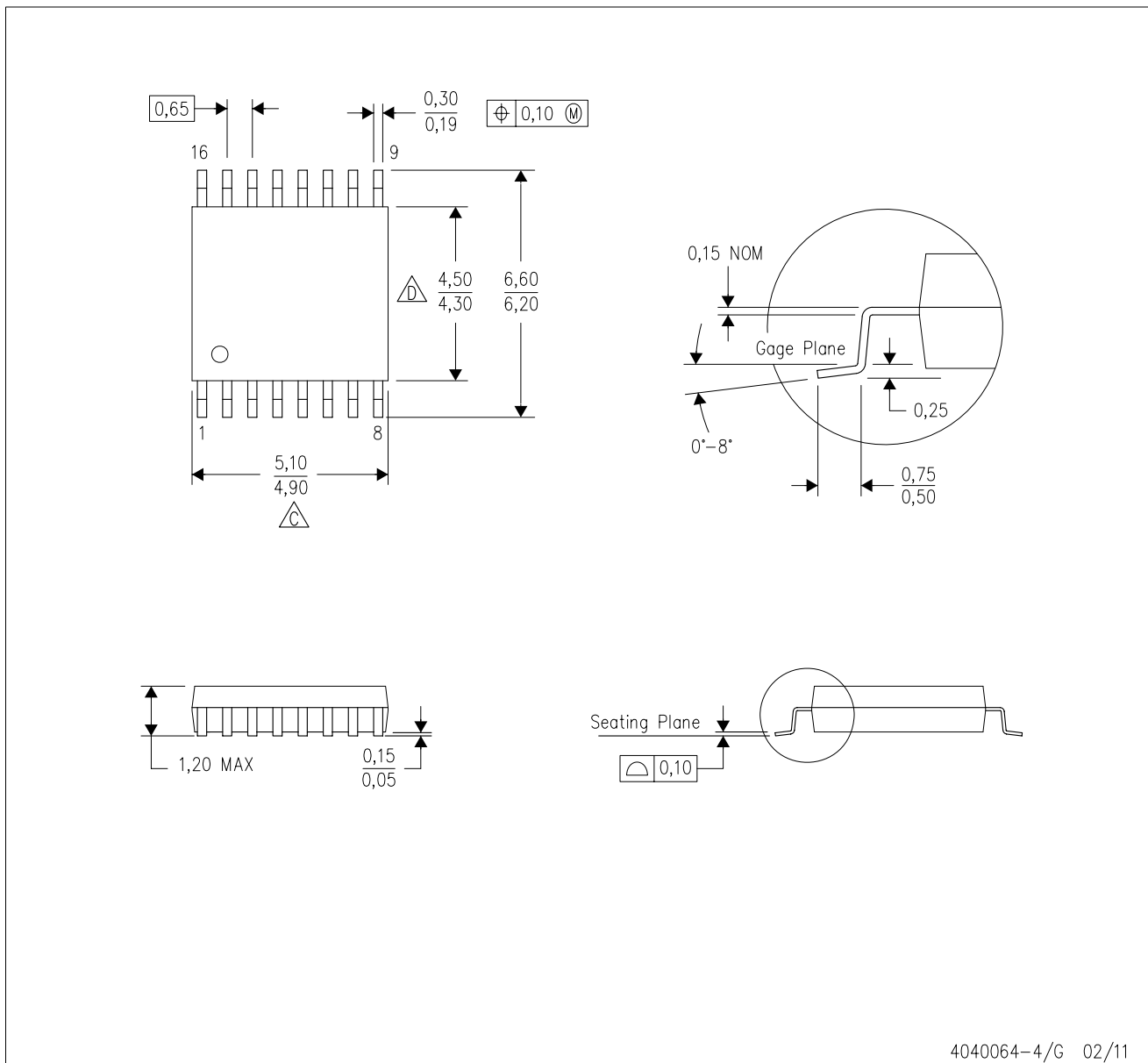
PLASTIC SMALL OUTLINE





- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE

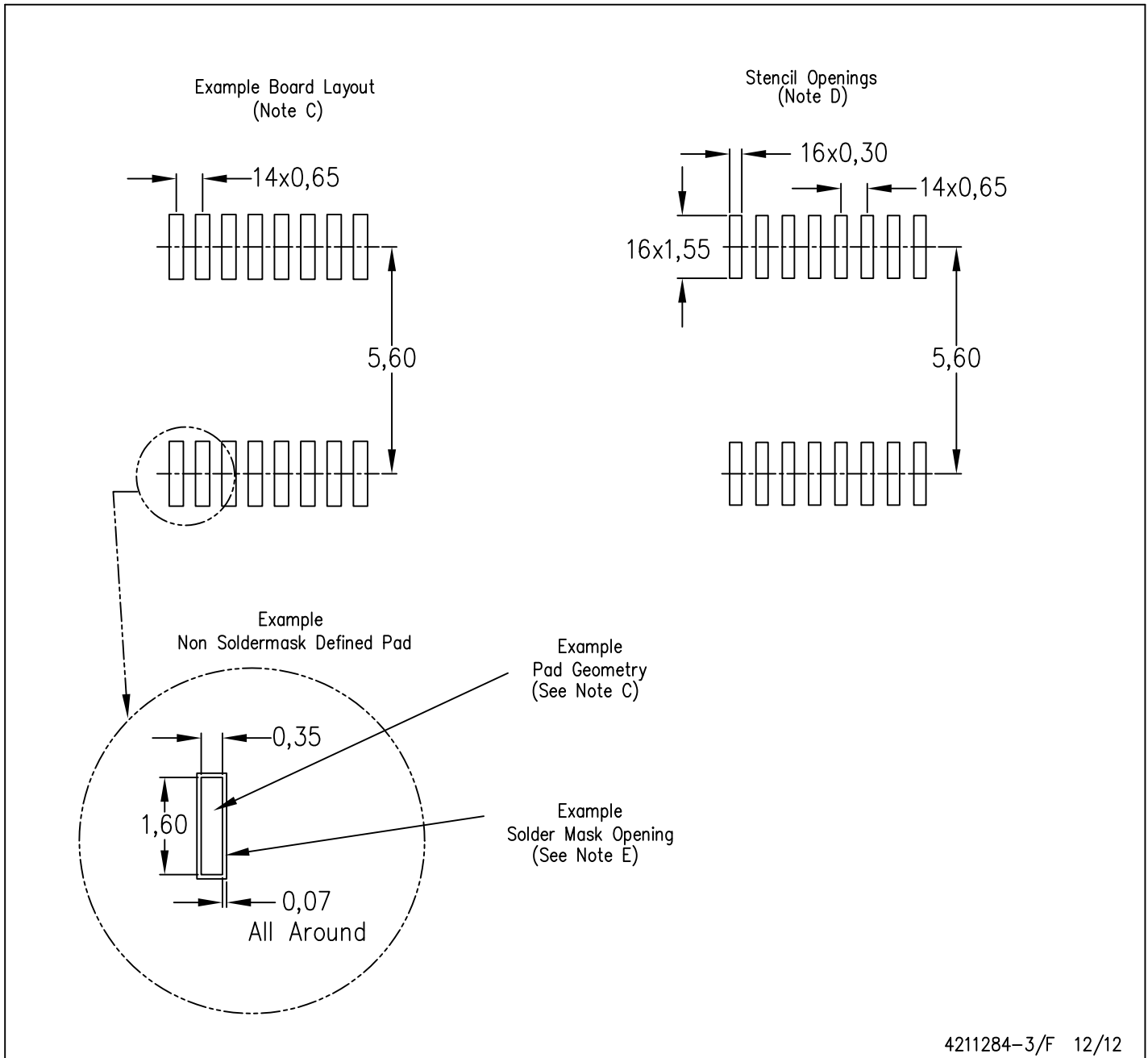


4040064-4/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  -  Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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